

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Serial No: 09/834,696

Filed: April 12, 2001

For: METHOD OF MAKING A
SEMICONDUCTOR CHIP
PACKAGE

May 14, 2001

Commissioner of Patents and Trademarks
Washington, DC 20231

PRELIMINARY AMENDMENT

Please amend the Application as follows.

In The Specification

Page ²~~1~~, line 1, insert the following.

~Cross Reference to Related Applications

This is a continuation of Application Serial No. 08/910,500 filed August 4, 1997. ~

PRELIMINARY AMENDMENT--1

MICR135.02
09/834,696

#2 Sub B1

19.(new) A semiconductor chip package, comprising:
a semiconductor chip;
conductive leads electrically connected to and extending over a surface of the chip;
encapsulating material covering at least a portion of the chip and at least a portion of the conductive leads; and
electrodes each having a first portion disposed in the encapsulating material and contacting a conductive lead and a second portion protruding from the encapsulating material.

20.(new) A semiconductor chip package according to Claim 19, wherein the conductive leads extend out through the encapsulating material.

21.(new) A semiconductor chip package according to Claim 19, wherein the conductive leads are fully encapsulated within the encapsulating material.

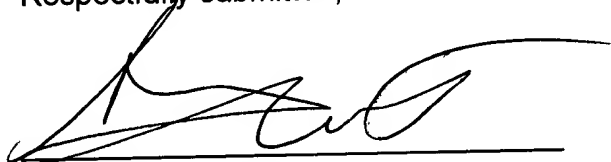
22.(new) A semiconductor chip package, comprising:
a semiconductor chip having bond pads thereon, the bond pads accessible from a surface of the chip;
conductive leads extending over and attached to the surface of the chip, each conductive lead electrically connected to a bond pad;
encapsulating material covering at least a portion of the surface of the chip, the bond pads and at least a portion of the conductive leads; and
electrodes each having a first portion disposed in the encapsulating material and contacting a conductive lead and a second portion protruding from the encapsulating material.

REMARKS

New Claims 19 and 22 are similar to Claims 1 and 6 in U.S. Patent No. 5,677,566 (the grandparent to this case). The new claims do not expressly recite openings for the electrodes. Rather, the new claims recite that the electrodes have a first portion disposed in the encapsulating material and contacting a conductive lead and a second portion protruding from the encapsulating material. This change is intended to clarify that a discrete opening is not necessary. Although Applicants believe the claims in U.S. Patent No. 5,677,566 and other related cases that recite an opening cover all types of openings (discrete or otherwise), the new claims are added to specifically cover the situation in which the chip, leads and electrodes might be encapsulated as an assembly and, hence, the electrodes would lie in an opening created by the electrode itself during encapsulation, rather than forming the electrode in a discrete opening in the encapsulating material.

Also, new Claims 19 and 22 omit reference to an "upper" surface to account for the possibility that a creative litigator might argue "upper" is limiting depending on how you hold the chip or how the chip is held in the assembly equipment. No such limitation was intended in the original claims and the new claims manifest this intent.

Respectfully submitted,



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